

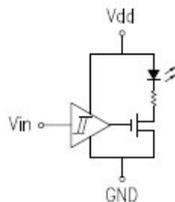
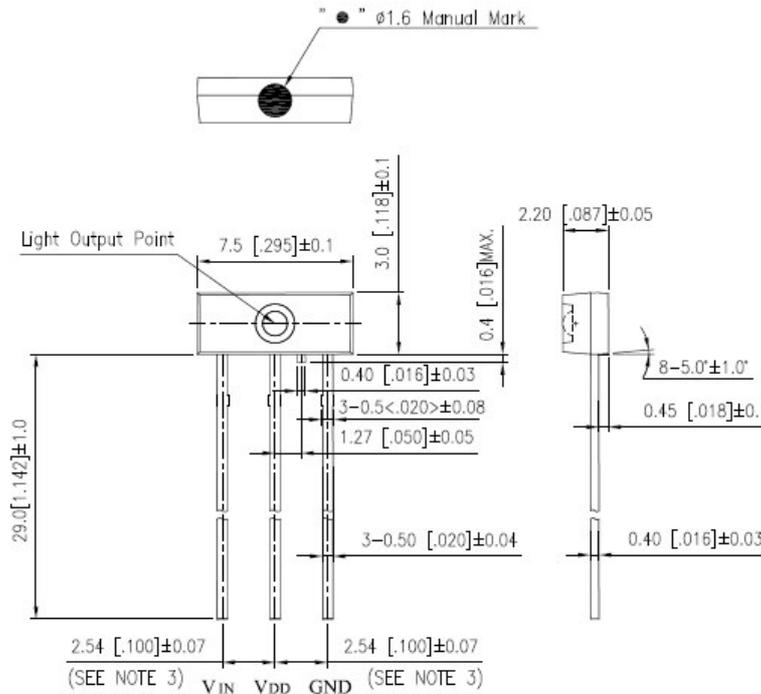
**FEATURES**

- \* TTL INTERFACE COMPATIBLE
- \* HIGH SPEED OPTIC SIGNAL TRANSMISSION
- \* BUILT-IN LED DRIVER
- \* BUILT-IN CURRENT LIMIT RESISTOR
- \* LOW POWER CONSUMPTION

V <sub>DD</sub>	V <sub>in</sub>	LED	V <sub>DD</sub>	V <sub>in</sub>	LED
2.75V ~ 3.3V	HIGH	ON	FLOATING	HIGH	OFF
2.75V ~ 3.3V	LOW	OFF	FLOATING	LOW	OFF
2.75V ~ 3.3V	FLOATING	OFF			

- \* WATER CLEAR EPOXY COMPOUND PACKAGED.

**PACKAGE DIMENSIONS**



**NOTES:**

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.1mm(.004") unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. Mark color : Brown.



# LITE-ON TECHNOLOGY CORPORATION

Property of Lite-On Only

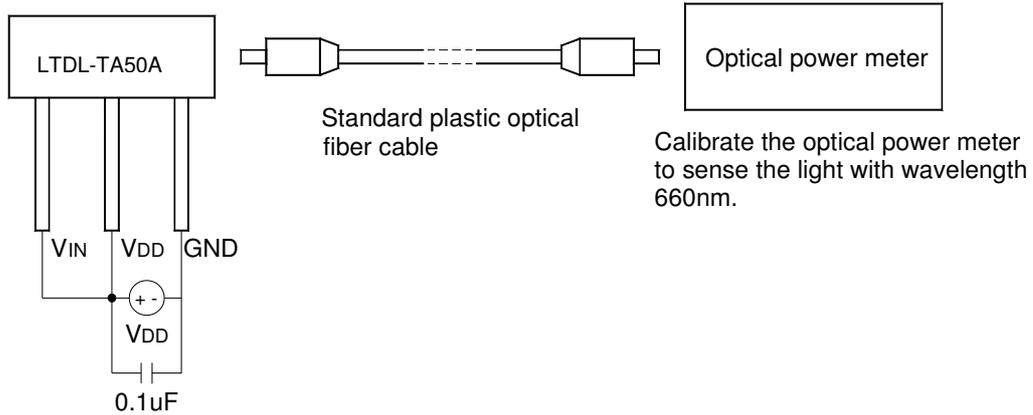
## ABSOLUTE MAXIMUM RATINGS AT TA=25°C

PARAMETER	MAXIMUM RATING	UNIT
Supply Voltage (V <sub>DD</sub> )	-0.5 ~ +7	V
Input Voltage (V <sub>IN</sub> )	-0.5 ~ V <sub>DD</sub> +0.5	V
Power Dissipation (P)	120	mW
Operating Temperature Range	-25 °C to + 70 °C	
Storage Temperature Range	-40 °C to + 85 °C	
Lead Soldering Temperature [1.6mm(.063") From Body]	260°C for 5 Seconds	

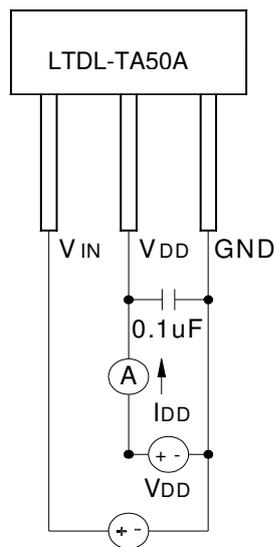
## ELECTRICAL OPTICAL CHARACTERISTICS AT TA=25°C

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION
Transmission Speed	T <sub>s</sub>	—	—	50	Mbps	NRZ signal
Operating Voltage	V <sub>DD</sub>	2.75	—	5.25	V	
Peak Emission Wavelength	λ <sub>Peak</sub>	630	650	690	nm	
Fiber coupling light output	P <sub>c</sub>	-21	-17	-15	dBm	*1
Dissipation current	I <sub>DD</sub>	0.5	—	10	mA	*2
High level input voltage	V <sub>IH</sub>	2	—	—	V	
Low level input voltage	V <sub>IL</sub>	—	—	0.8	V	
“Low→High”propagation delay time	t <sub>PLH</sub>	—	—	50	ns	*3
“High→Low”propagation delay time	t <sub>PHL</sub>	—	—	50	ns	
Pulse width distortion	Δ t <sub>w</sub>	-8	—	8	ns	
Jitter	Δ t <sub>j</sub>	—	—	8	ns	

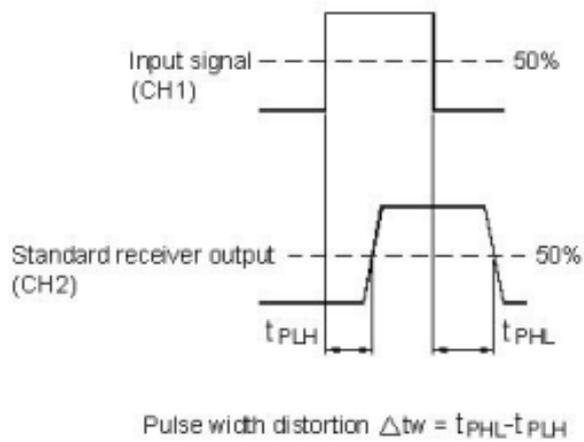
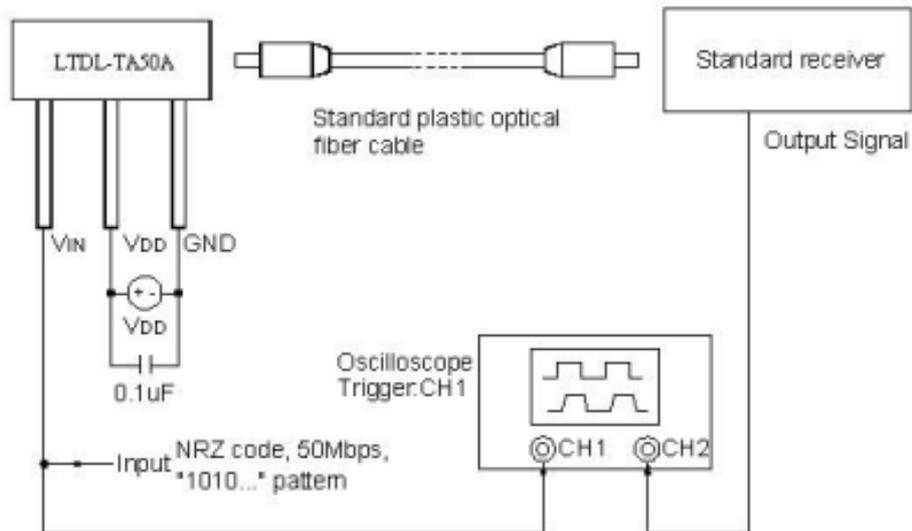
## \*1 Measuring method of optical output coupling power



## \*2 Power dissipation measuring method



**\*3 Measuring pulse response**





## CAUTIONS

### 1. Storage

■ For the devices which are stored out of their original packaging and storage ambient should not exceed 30°C temperature 60% relative humidity for more than 168 hrs, it is better to bake them at about 100±5°C for at least 4 hours before assembling.

### 2. ESD (Electrostatic Discharge)

Static Electricity or power surge will damage the devices.

Suggestions to prevent ESD damage:

- Use of a conductive wrist band or anti-electrostatic glove when handling these devices.
- All devices, equipment, and machinery must be properly grounded.
- Work tables, storage racks, etc. should be properly grounded.
- Use ion blower to neutralize the static charge which might have built up on surface of the device's plastic lens as a result of friction between devices during storage and handling.